

N-Channel MOSFET

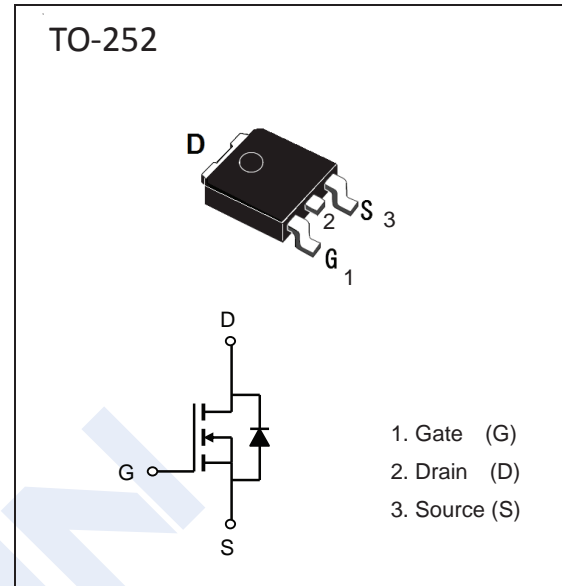
2KK5113

■ Features

- $V_{DS(V)} = 650\text{ V}$
- $I_D = 11\text{ A}$
- $R_{DS(ON)} < 360\text{m}\Omega @ V_{GS} = 10\text{V}$
- Low FOM $R_{DS(ON)} \times Q_G$
- Better EMI
- 100% UIS tested

■ Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Rating | Unit | |
|--------------------------------------------------------------|------------------------|-------------------------|--------------------|---|
| Drain-Source Voltage | V_{DS} | 650 | V | |
| Gate-Source Voltage | V_{GS} | ± 30 | | |
| Drain Current - Continuous ^(Note 1) | I_D | $T_C=25^\circ\text{C}$ | 11 | |
| | | $T_C=100^\circ\text{C}$ | 7 | |
| Drain Current - Pulsed ^(Note 2) | I_{DM} | 33 | A | |
| Single Pulsed Avalanche Energy ^(Note 3) | EAS | 80 | mJ | |
| MOSFET dv/dt ruggedness | dv/dt | 130 | V/ns | |
| Reverse diode dv/dt | | 33 | | |
| Power Dissipation | $T_C=25^\circ\text{C}$ | P_D | 23 | W |
| Thermal Resistance, Junction- to-Ambient ^(Note 4) | $R_{\theta JA}$ | 62.5 | $^\circ\text{C/W}$ | |
| Thermal Resistance, Junction- to-Case | $R_{\theta JC}$ | 5.4 | | |
| Operating and Storage Temperature Range | T_J, T_{stg} | -55 to 150 | $^\circ\text{C}$ | |

Notes:

1. The max drain current limited by maximum junction temperature
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3. $L = 10\text{ mH}$, $V_{DD} = 150\text{V}$, $I_{AS} = 4\text{A}$, $R_G = 25\ \Omega$, Starting $T_J = 25\ ^\circ\text{C}$
4. Mount on minimum PCB layout

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■ Electrical Characteristics (T_J=25°C unless otherwise noted)

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|---------------------------------------------------------------|---------------------|-----------------------------------------------------------------------------------------------|-----|-------|------|------|
| Static Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | V _{DSS} | I _D =250μA, V _{GS} =0V | 650 | | | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =650V, V _{GS} =0V | | | 1 | μA |
| | | V _{DS} =650V, V _{GS} =0V, T _J =150°C | | | 100 | |
| Gate-Body Leakage Current | I _{GSS} | V _{DS} =0V, V _{GS} =±30V | | | ±100 | nA |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250μA | 2.5 | | 4.5 | V |
| Static Drain-Source On-Resistance | R _{DS(on)} | V _{GS} = 10V, I _D = 5.5A | | 280 | 360 | mΩ |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C _{iss} | V _{GS} =0V, V _{DS} =100V, f=1MHz | | 841 | | pF |
| Output Capacitance | C _{oss} | | | 45.1 | | |
| Reverse Transfer Capacitance | C _{rss} | | | 2.8 | | |
| Gate Resistance | R _G | F = 1 MHz | | 5 | | Ω |
| Switching Characteristics | | | | | | |
| Total Gate Charge | Q _g | V _{DD} = 520V, I _D = 5.5A, V _{GS} = 10V | | 23.3 | | nC |
| Gate Source Charge | Q _{gs} | | | 5.5 | | |
| Gate Drain Charge | Q _{gd} | | | 9.7 | | |
| Turn-On DelayTime | t _{d(on)} | V _{DD} = 520V, I _D = 5.5A, V _{GS} = 10V, R _G = 25Ω | | 18.2 | | ns |
| Turn-On Rise Time | t _r | | | 25.8 | | |
| Turn-Off DelayTime | t _{d(off)} | | | 81.8 | | |
| Turn-Off Fall Time | t _f | | | 26.8 | | |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| Reverse Recovery Time | t _{rr} | V _{DD} = 100V, I _D = 5.5A, di/dt = 100A/μS | | 250 | | ns |
| Reverse Recovery Charge | Q _{rr} | | | 2.55 | | μC |
| Peak Reverse Recovery Current | I _{RRM} | | | -22.3 | | |
| Maximum Continuous Body-Diode Forward Current | I _S | | | | 11 | A |
| Maximum Pulsed Body-Diode Forward Current | I _{SM} | | | | 33 | |
| Diode Forward Voltage | V _{SD} | I _S =11A, V _{GS} =0V | | 0.85 | | V |

■ Marking

| | |
|---------|---------------|
| Marking | K5113 K*** |
|---------|---------------|

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Typical Characteristics

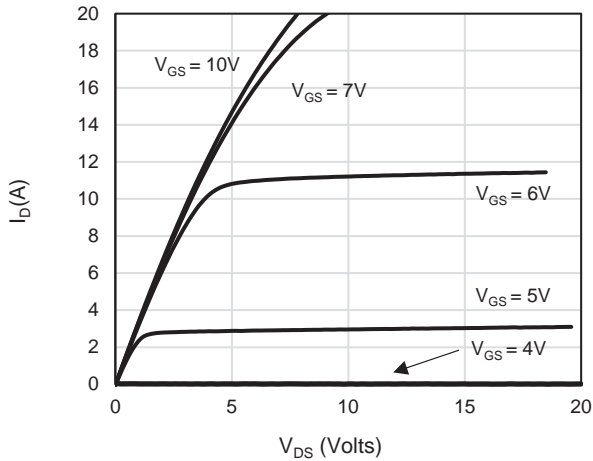


Figure 1: On-Region Characteristics

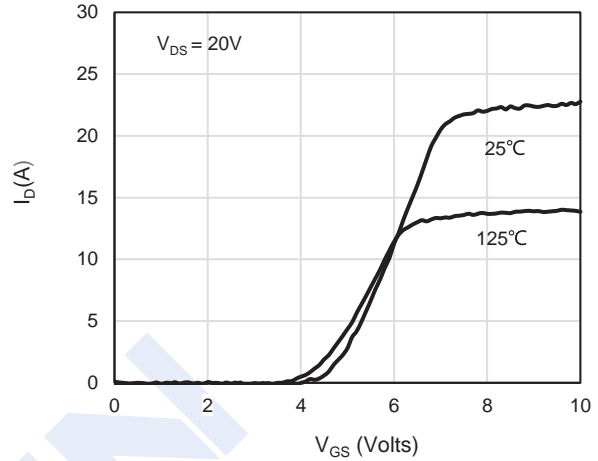


Figure 2: Transfer Characteristics

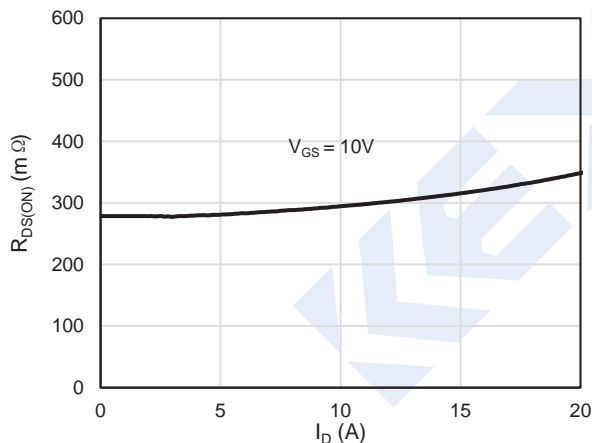


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

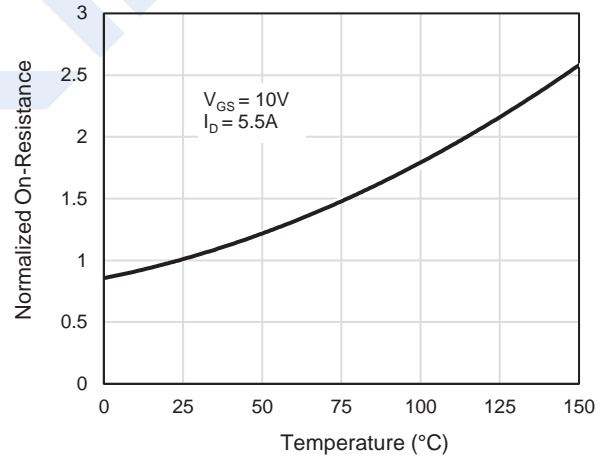


Figure 4: On-Resistance vs. Junction Temperature

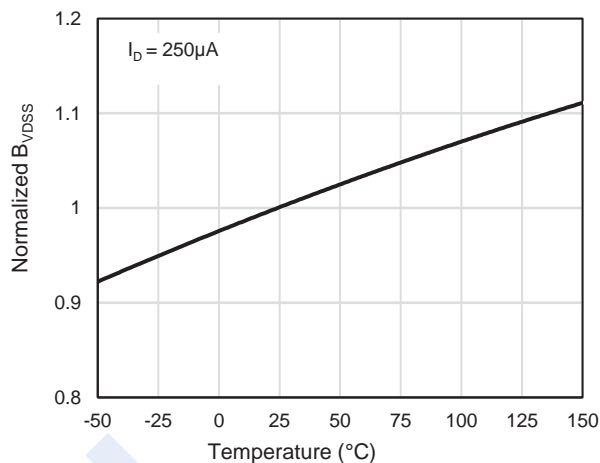


Figure 5: Breakdown Voltage vs. Junction Temperature

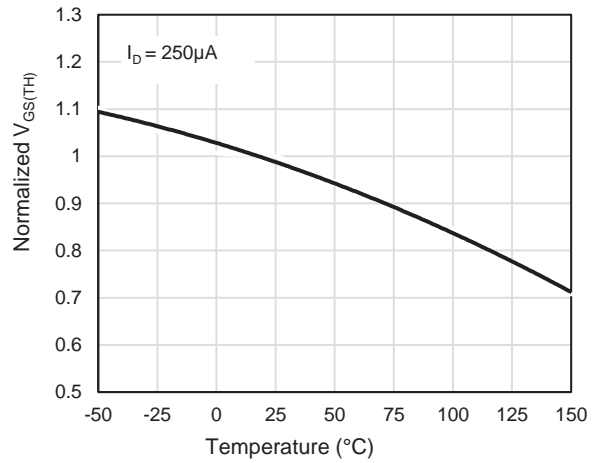


Figure 6: Threshold Voltage vs. Junction Temperature

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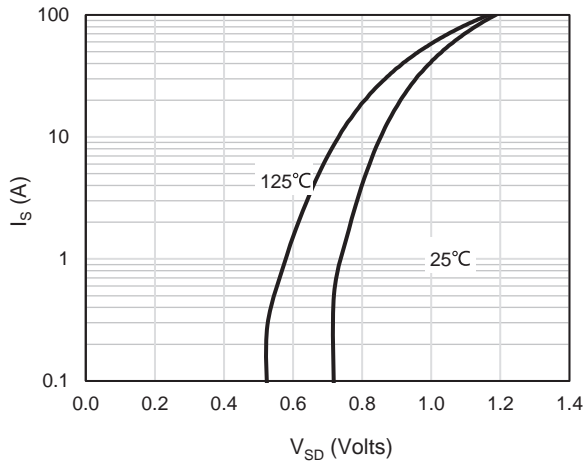


Figure 7: Body-Diode Characteristics

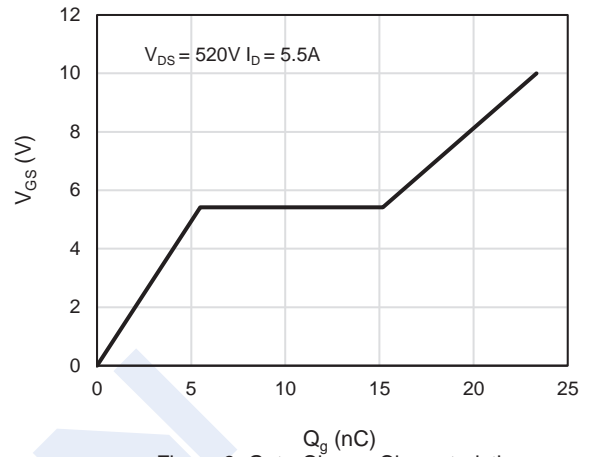


Figure 8: Gate-Charge Characteristics

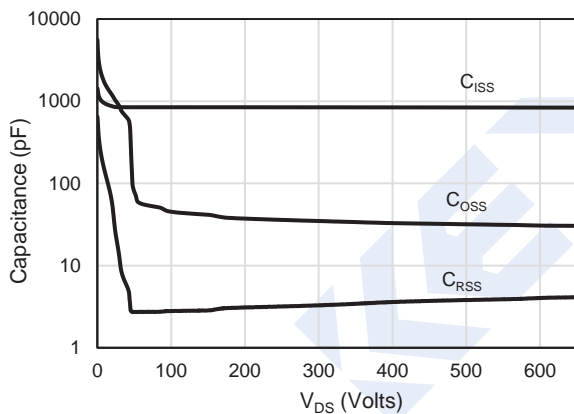


Figure 9: Capacitance Characteristics

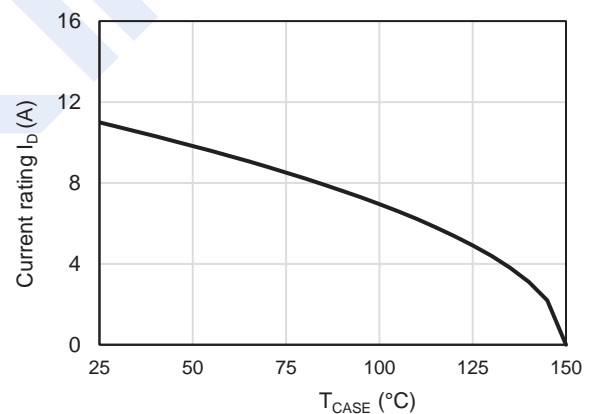


Figure 10: Current De-rating (Note 1)

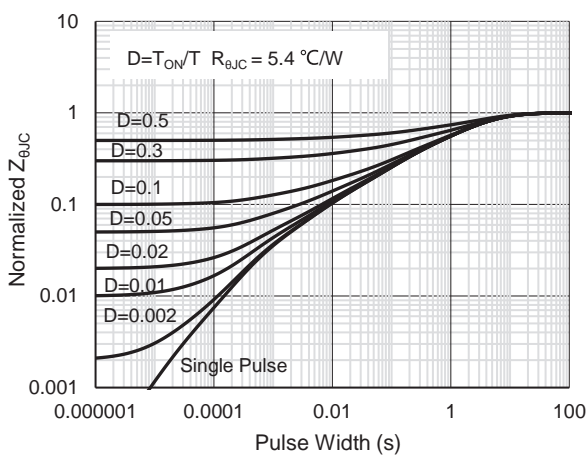


Figure 11: Normalized Maximum Transient Thermal Impedance

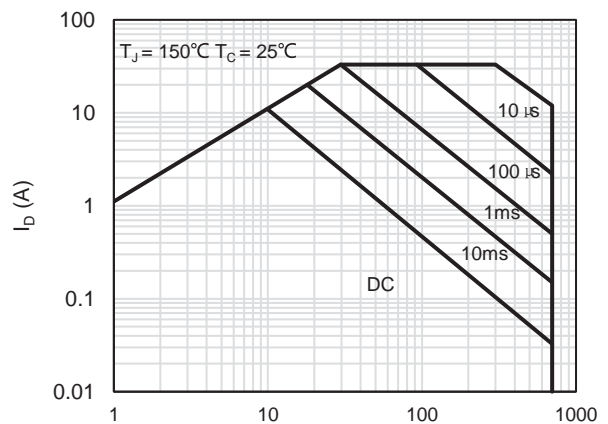


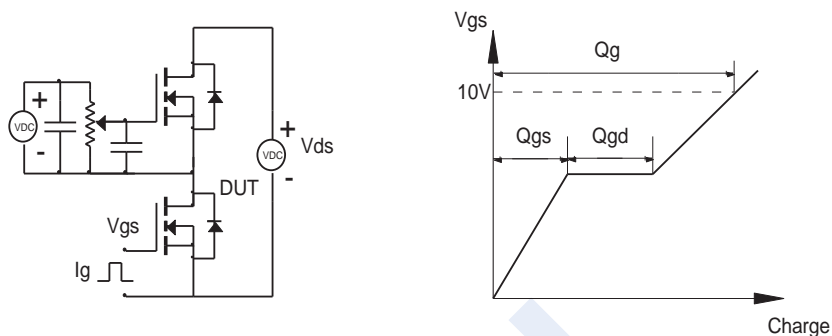
Figure 12: Maximum Forward Biased Safe Operating Area

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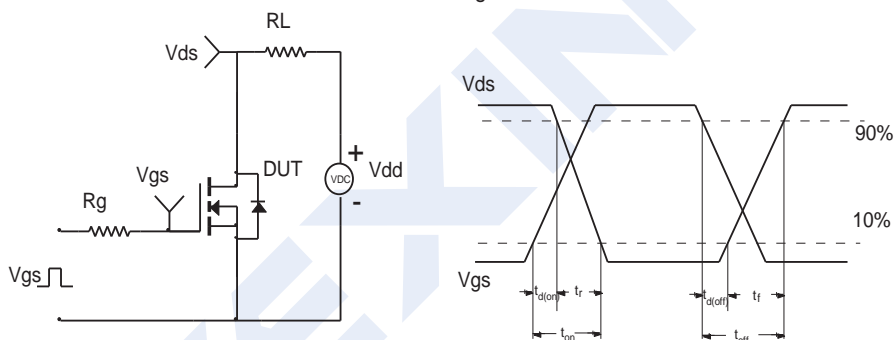
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■ Test Circuit and Waveform

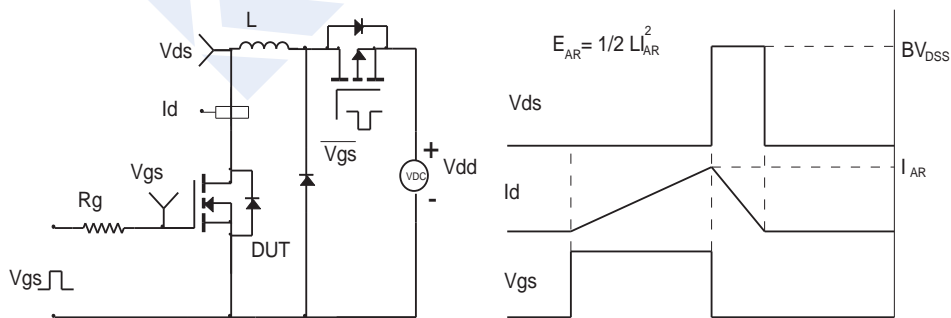
Gate Charge Test Circuit & Waveform



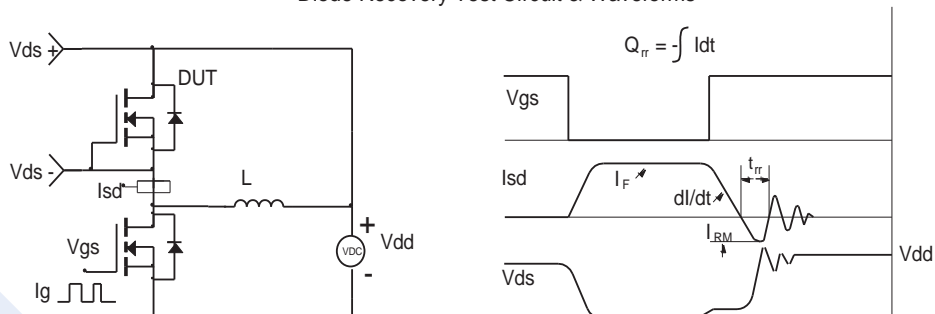
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



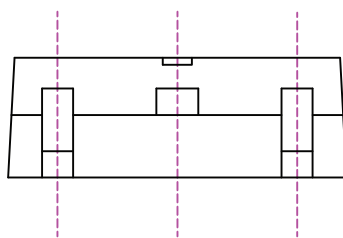
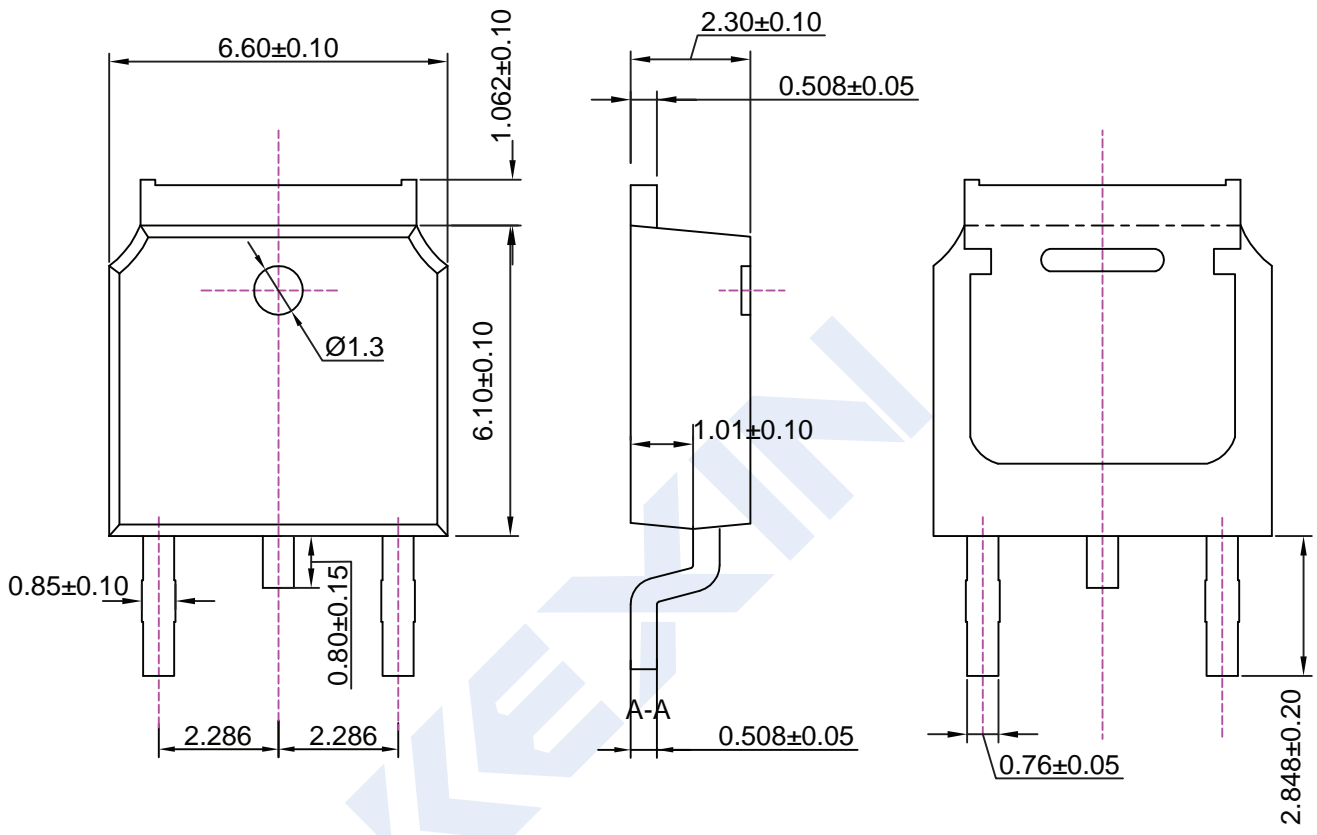
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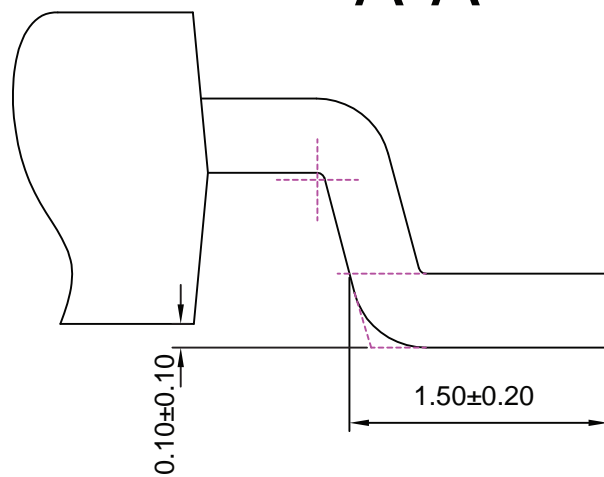
■ Package Dimension

TO-252

Units: mm



A-A



- Note:
1. General tolerance: ± 0.05 mm
 2. Controlling dimension: in millimeters